ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.												
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater						erials and M	ials and Mfg Information				
Supplier Inform	ation																
Company name* Company unique ID				ique ID		Unique ID Authority					Respons	Response Date*					
onsemi												2023-06	2023-06-08				
Contact Name			Title - Contact]	Phone - Contact*					Email -	Email - Contact*				
Product-Env-Stewa	rds	Product Enviro Compliance				NA					Produc	Product-Env-Stewards@onsemi.com					
Authorized Represen	Title - Representative]	Phone - Representative*				Email -	Email - Representative*							
Product-Env-Stewards			Product Enviro Compliance				NA NA					Produc	Product-Env-Stewards@onsemi.com				
Requeste	Item Number Mfr Item N LC717A30		em Number Mfr Item Name 'A30UR-NH TOUCH SENSOR 8CH				Effective Da	ate V	Version Ma		Manufacturing Site		Weigh	nt*	UOM	Unit Type	
					R 8CH		2023-06-08	PHN		PHM	PHM		20.0 mg		mg	Each	
Ianufacturing	Proccess Informatio	n													1		
Terminal l	al Plating / Grid Array Material		Terminal Base Alloy J		J-STD-020 M	020 MSL Rating		Peak Process Body Temperatu		ture N	are Max Time at Peak Tempe		erature Number of Reflow Cycles		les		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 3		3		260		С		30 seco		ds :	3			
Comments																	
TTENTION: MSL	3 Rated item requires B	ake and D	ry Pack (after	r electrical test)													
or more information	on regarding material co	nposition	please refer to	page 3													

RoHS Material Composition Declaration			Declaration Type *	Detail	ed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU ROHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).												
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.												
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted							
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.												
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.44	mg	Supplier	Silicon (Si)	7440-21-3		1.4308	mg
			Supplier	Polyimide	Proprietary Data		0.0092	mg
Die Attach	0.06	mg	Supplier	Epoxy resins	129915-35-1		0.0435	mg
			Supplier	Acrylic resins	Proprietary Data		0.0165	mg
Mold Compound-Black	13.8709	mg		Epoxy Phenol Resin	proprietary data		1.5258	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0277	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		11.7625	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.5548	mg
Substrate and Solder Mask	4.4	mg	В	Nickel (Ni)	7440-02-0		0.3164	mg
			Supplier	Gold (Au)	7440-57-5		0.0682	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data		2.6893	mg
			Supplier	Copper (Cu)	7440-50-8		1.3262	mg
Wire Bond	0.2291	_	Supplier	Palladium (Pd)	7440-05-3		0.0023	mg
			Supplier	Gold (Au)	7440-57-5		0.2268	mg